

<b>Interview Summary</b>	Application No. <del>10/664,129</del> 10/664,129		Applicant(s) <del>KATO ET AL</del> <i>SC. Munekata</i>
	Examiner Sikyin Ip		Art Unit 1742

All participants (applicant, applicant's representative, PTO personnel):

(1) Sikyin Ip.

(3) Mr. SHOICHI HIROSE

(2) Michael Tobias.

(4) \_\_\_\_\_

Date of Interview: 22 September 2004.

Type: a) ☐ Telephonic b) ☐ Video Conference  
c) ☒ Personal [copy given to: 1) ☐ applicant 2) ☒ applicant's representative]

Exhibit shown or demonstration conducted: d) ☐ Yes e) ☒ No.  
If Yes, brief description: \_\_\_\_\_

Claim(s) discussed: All.

Identification of prior art discussed: All.

Agreement with respect to the claims f) ☐ was reached. g) ☒ was not reached. h) ☐ N/A.

Substance of Interview including description of the general nature of what was agreed to if an agreement was reached, or any other comments: X.

(A fuller description, if necessary, and a copy of the amendments which the examiner agreed would render the claims allowable, if available, must be attached. Also, where no copy of the amendments that would render the claims allowable is available, a summary thereof must be attached.)

THE FORMAL WRITTEN REPLY TO THE LAST OFFICE ACTION MUST INCLUDE THE SUBSTANCE OF THE INTERVIEW. (See MPEP Section 713.04). If a reply to the last Office action has already been filed, APPLICANT IS GIVEN ONE MONTH FROM THIS INTERVIEW DATE, OR THE MAILING DATE OF THIS INTERVIEW SUMMARY FORM, WHICHEVER IS LATER, TO FILE A STATEMENT OF THE SUBSTANCE OF THE INTERVIEW. See Summary of Record of Interview requirements on reverse side or on attached sheet.

*\* The Applicants' Japanese representative presented arguments MHT evidence that the inventors had found for the first time the effect of P on reducing MHT improving wettability in terms of zero crossing time in soldering. The Applicant's Japanese representative emphasized the great commercial importance of the invention to the industry and the ability of the invention to reduce manufacturing costs by permitting an increase in the line speed of a soldering line. MHT*

Examiner Note: You must sign this form unless it is an Attachment to a signed Office action.

*[Signature]*  
Examiner's signature, if required